

MECHANICAL CASE OUTLINE

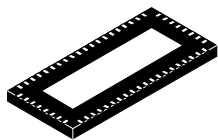
PACKAGE DIMENSIONS

ON Semiconductor®

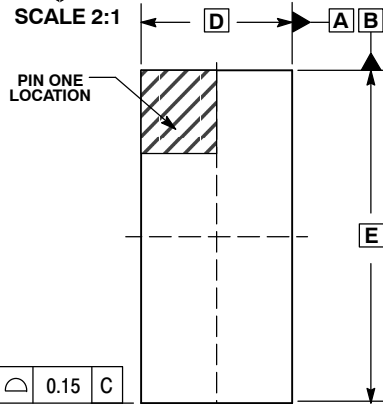


WQFN56 5x11, 0.5P
CASE 510AK-01
ISSUE A

DATE 02 MAR 2010



SCALE 2:1



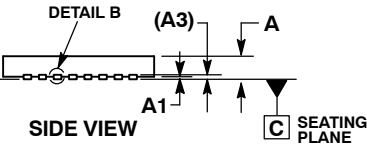
ϕ	0.15	C
∇	0.15	C

TOP VIEW

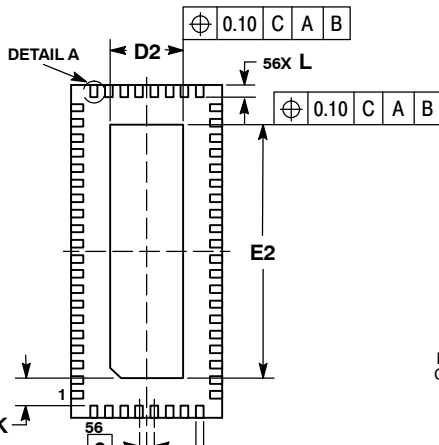
∇	0.10	C
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∇	0.08	C
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NOTE 4



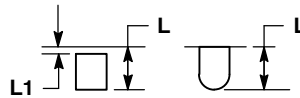
SIDE VIEW



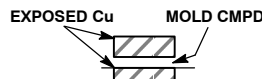
BOTTOM VIEW

ϕ	0.10	C	A	B
ϕ	0.05	C		

NOTE 3

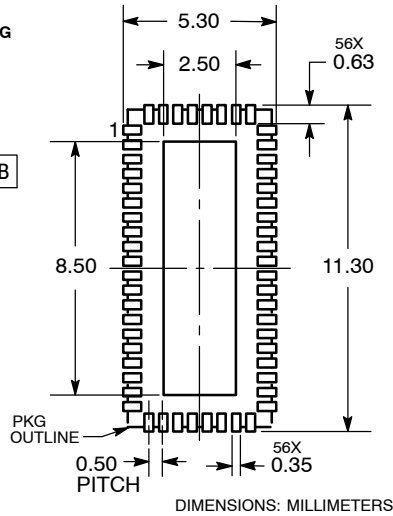


DETAIL A
ALTERNATE
CONSTRUCTIONS



DETAIL B
ALTERNATE
CONSTRUCTION

RECOMMENDED SOLDERING FOOTPRINT



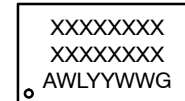
DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	5.00	BSC
D2	2.30	2.50
E	11.00	BSC
E2	8.30	8.50
e	0.50	BSC
K	0.20	MIN
L	0.30	0.50
L1	---	0.15

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WQFN56 5x11, 0.5P	PAGE 1 OF 2

